VCP Recommended Reference

Plating Line				Technology			Rigid Panel Thickness		Flex Panel (FPC)	Anode Type		500mm deep FPC panel installation dimensions		635mm deep panel installation dimensions		730mm deep panel installation dimensions	
General classification	Medium classification	Rectifier	Cathode flight bar	Panel plating	Pattern plating	Hole filling	0.3-3.2mm	0.05-3.2mm	0.036-1.2mm	Soluble	insoluble	(mm) Width	(mm) Height	(mm) Width	(mm) Height	(mm) Width	(mm) Height
Transfer-type VCP	Single-row Upper and Lower transfer-type VCP	DC	Top clamp	●	●	●	●	●	●	●	●	2950	3800	2950	4000	2950	4200
		Pulse-electroplating		●	0	*	●	●	*	●	*	*	*	3650	4000	3650	4200
		DC	Upper and lower clip frame	●	●	●	●	●	●	●	●	2950	4800	2950	5000	2950	5200
		Pulse-electroplating		●	0	*	●	●	*	●	*	*	*	3650	5000	3650	5200
	Double-row Upper and Lower Transfer-type DVCP	DC	Top clamp	●	●	●	●	●	●	●	●	4350	3800	4350	4000	4350	4200
		Pulse-electroplating		●	0	*	●	●	*	●	*	*	*	5500	4000	5500	4200
		DC	Upper and lower clip frame	●	●	●	●	●	●	●	●	4350	4800	4350	5000	4350	5200
		Pulse-electroplating		●	0	*	●	●	*	●	*	*	*	5500	5000	5500	5200
	Single-row Li-transfer-type UVCP	DC	Top clamp	●	●	●	●	●	●	●	●	5120	3500	5120	3600	5120	3700
		Pulse-electroplating		●	0	*	●	●	*	●	*	*	*	5120	3600	5120	3700
		DC	Upper and lower clip frame	●	●	●	●	●	●	●	●	5120	3600	5120	3750	5120	3850
		Pulse-electroplating		●	0	*	●	●	*	●	*	*	*	5120	3750	5120	3850
	Double-row ~~LI-transfer-type UDVCP~~	DC	Top clamp	●	●	●	●	●	●	●	●	7000	3500	7000	3600	7000	3700
		Pulse-electroplating		●	0	*	●	●	*	●	*	*	*	7000	3600	7000	3700
		DC	Upper and lower clip frame	●	●	●	●	●	●	●	●	7000	3600	7000	3750	7000	3850
		Pulse-electroplating		●	0	*	●	●	*	●	*	*	*	7000	3750	7000	3850
Integrated-type EVCP	EVCP Integrated-type	DC	Top clamp	●	*	*	●	*	*	●	●	*	*	2350	3600	2350	3700
		Pulse-electroplating		●	*	*	●	*	*	●	*	*	*	2350	3750	2350	3850

● Applicable

* Not applicable

○ Applicable for copper plating, not applicable for tin plating

1. No insoluble anode has been used in Pulse-electroplating

2. -Integrated type is not recommended for pattern plating nor hole filling process, and is not recommended for manufacturing thin panel